



Material Content Data Sheet



Sales Product Name	SAK-XC2298H-200F100L AB			Issued		29. August 2013		
MA#	MA001049040							
Package	PG-LQFP-176-12			Weight*		2017.17 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	71.686	3.55	3.55	35538	35538
leadframe	inorganic material	phosphorus	7723-14-0	0.149	0.01		74	
	non noble metal	zinc	7440-66-6	0.594	0.03		295	
	non noble metal	iron	7439-89-6	11.887	0.59		5893	
	non noble metal	copper	7440-50-8	482.643	23.93	24.56	239268	245530
wire	noble metal	gold	7440-57-5	4.995	0.25	0.25	2476	2476
encapsulation	organic material	carbon black	1333-86-4	7.063	0.35		3502	
	plastics	epoxy resin	-	190.712	9.45		94544	
	inorganic material	silicondioxide	60676-86-0	1214.905	60.22	70.02	602282	700328
leadfinish	non noble metal	tin	7440-31-5	15.144	0.75	0.75	7507	7507
plating	noble metal	silver	7440-22-4	2.988	0.15	0.15	1482	1482
glue	plastics	epoxy resin	-	3.600	0.18		1785	
	noble metal	silver	7440-22-4	10.800	0.54	0.72	5354	7139
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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